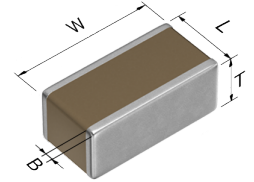


C1632X5R0J475M130AC



TDK item description C1632X5R0J475MT****

Applications	Commercial Grade
Feature	Low ESL Reverse Geometry
Series	C1632 [EIA 0612]
Status	Obsolete Discontinue Issue Date : Apr.28, 2018 Last Purchase Order Date : Oct.31, 2018 Last Shipment Date : Mar.31, 2019



Size	
Length(L)	1.60mm ±0.20mm
Width(W)	3.20mm ±0.20mm
Thickness(T)	1.30mm ±0.15mm
Terminal Width(B)	0.20mm Min.
Recommended Land Pattern (PA)	0.75mm Nom.
Recommended Land Pattern (PB)	0.73mm Nom.
Recommended Land Pattern (PC)	3.20mm Nom.

Electrical Characteristics	
Capacitance	4.7µF ±20%
Rated Voltage	6.3VDC
Temperature Characteristic	X5R(±15%)
Dissipation Factor (Max.)	5%
Insulation Resistance (Min.)	21MΩ

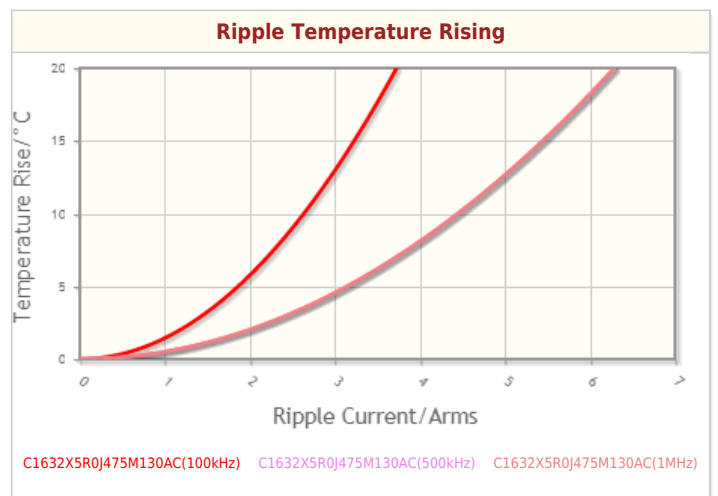
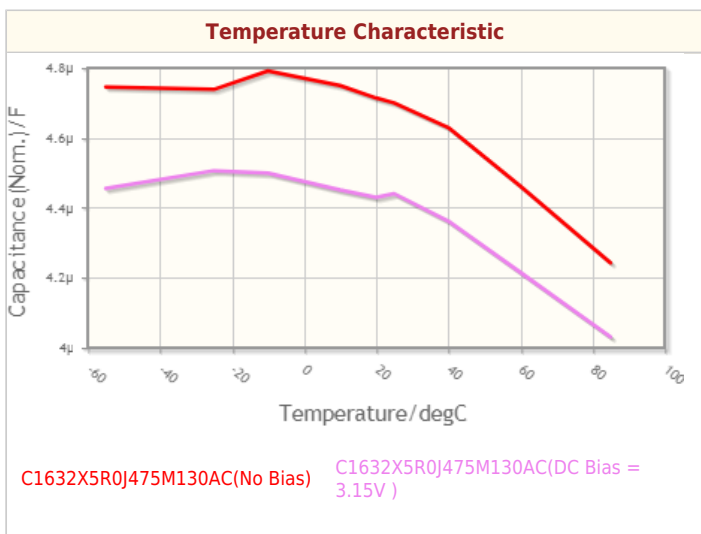
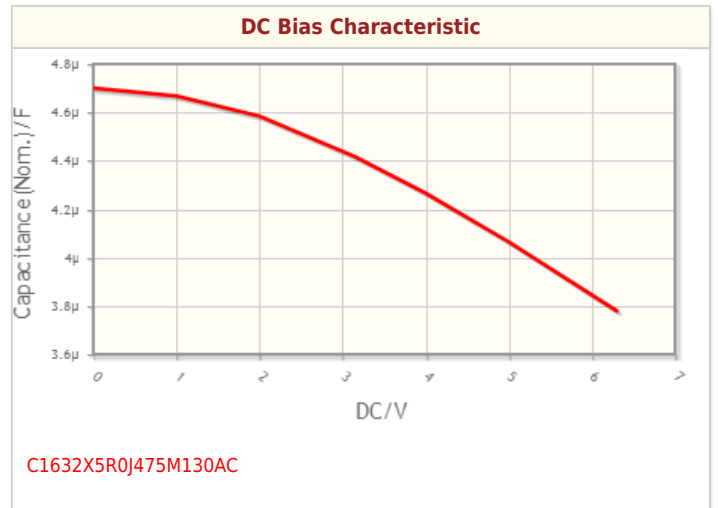
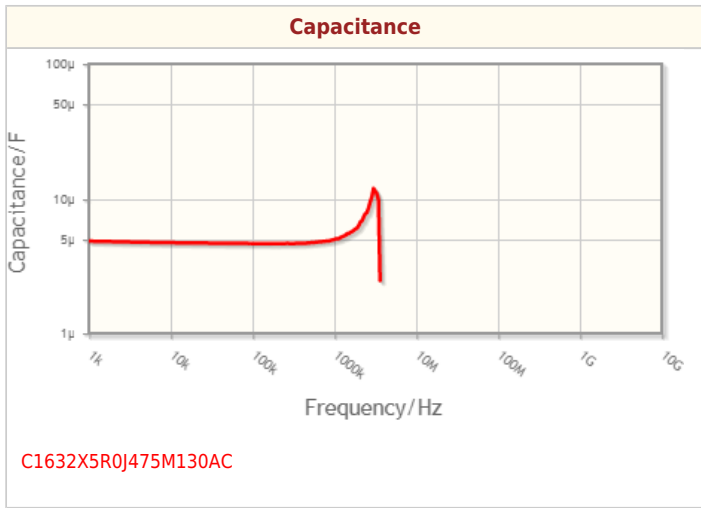
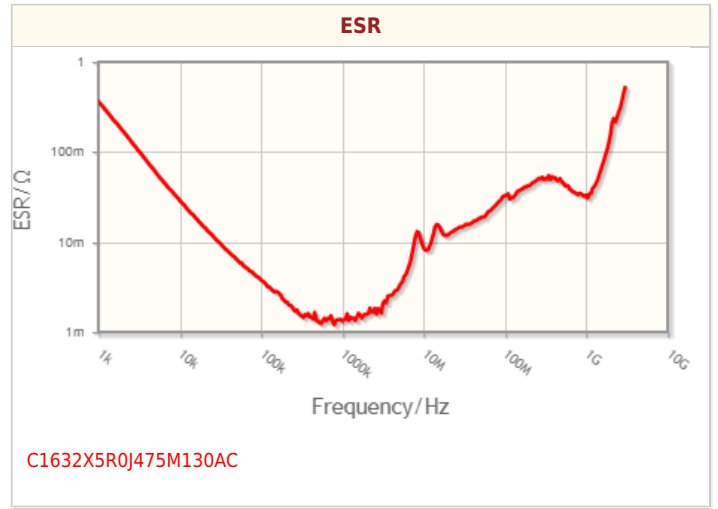
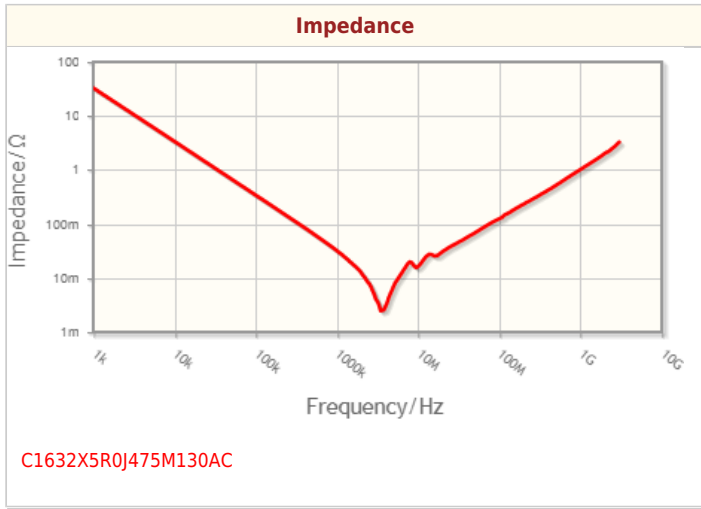
Other	
Soldering Method	Reflow
AEC-Q200	No
Packing	Blister (Plastic)Taping [180mm Reel]
Package Quantity	2000pcs

! Images are for reference only and show exemplary products.
 ! This PDF document was created based on the data listed on the TDK Corporation website.
 ! All specifications are subject to change without notice.

C1632X5R0J475M130AC



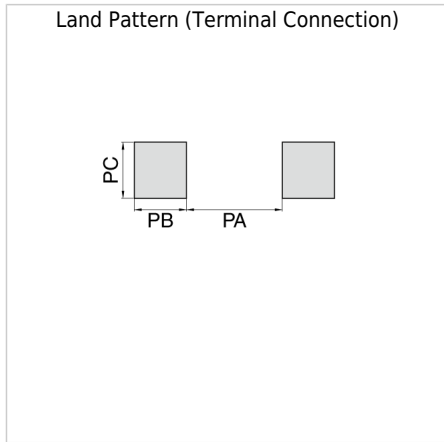
Characteristic Graphs(This is reference data, and does not guarantee the products characteristics.)



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Associated Images



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